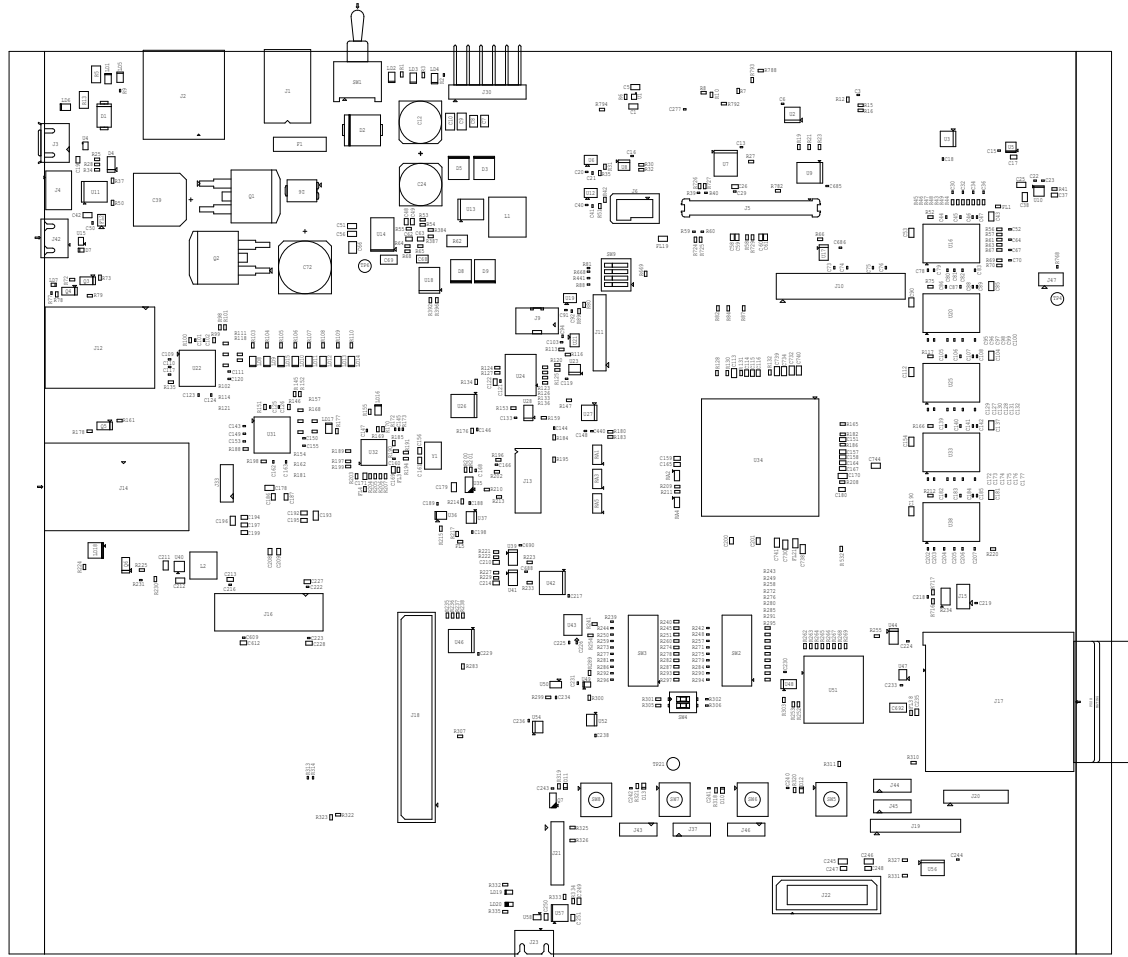



# PROC062B (001) ASSEMBLY TOP

## ASSEMBLY NOTES:-

- 1 - All MSL components should be baked as per JEDEC standard.
- 2 - PCB should be baked at 120 degree for 8 hours.
- 3 - Board assembly must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
- 4 - These assemblies are ESD sensitive, ESD precautions shall be observed.
- 5 - These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- 6 - Provide serial numbers to the assembled boards for identification.
- 7 - The assembled board are wrapped in ESD Covers(individual) and packed securely before shipment.

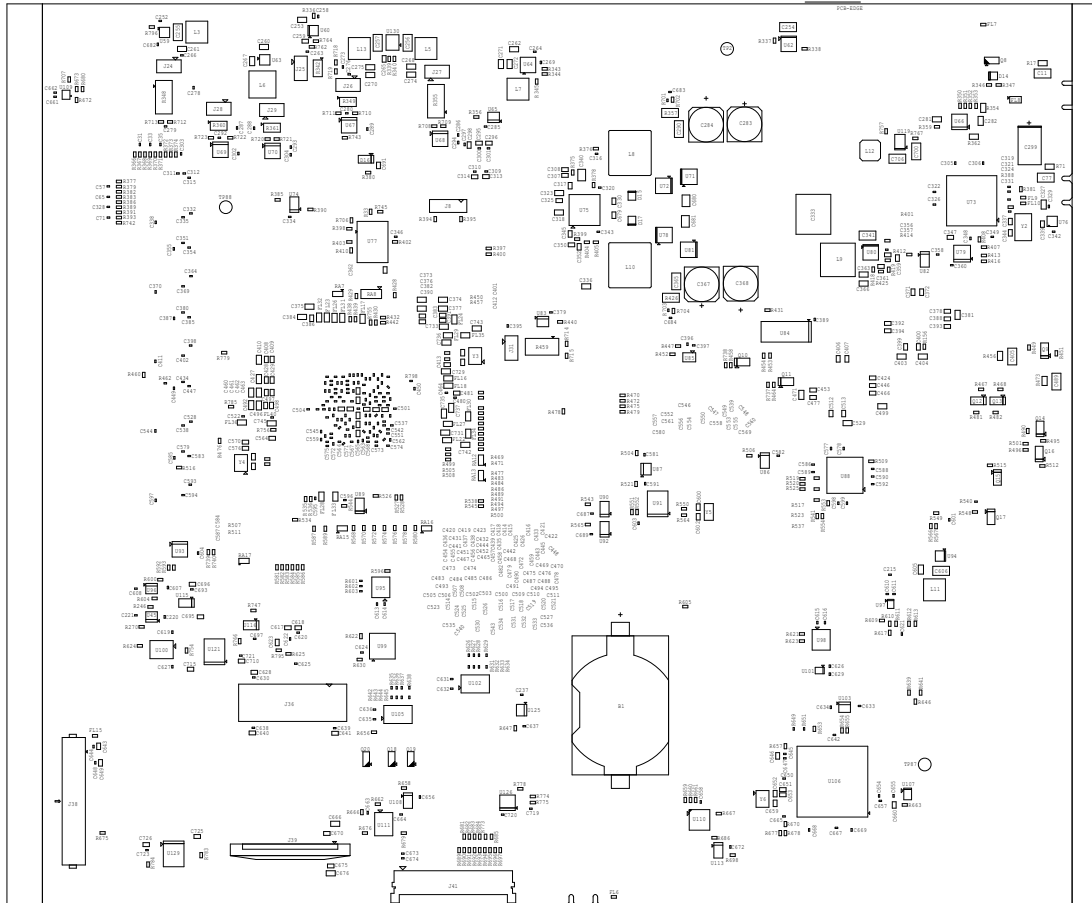



		TEXAS INSTRUMENTS		PROC062
BOARD NAME: AM654x EVM PROCESSOR BOARD		REV: B	DESCRIPTION: TOP ASSEMBLY V1	
SCALE: 1		DATE: 09/04/2021	SHEET 1 OF 2	

# PROC062B (001) ASSEMBLY BOTTOM

## ASSEMBLY NOTES:-

- 1 - All MSL components should be baked as per JEDEC standard.
- 2 - PCB should be baked at 120 degree for 8 hours.
- 3 - Board assembly must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
- 4 - These assemblies are ESD sensitive, ESD precautions shall be observed.
- 5 - These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- 6 - Provide serial numbers to the assembled boards for identification.
- 7 - The assembled board are wrapped in ESD Covers(individual) and packed securely before shipment.



		TEXAS INSTRUMENTS		PROC062
BOARD NAME:AM654K EVM PROCESSOR BOARD		REV: B	DESCRIPTION: BOTTOM ASSEMBLY V1	
SCALE: 1		DATE: 09/04/2021	SHEET 2 OF 2	